

1. ECN #: 233201

2. Date of Announcement: September 22, 2014

3. Series:

- TFM - .050 X .050 MICRO STRIPS

4. Part #'s Affected

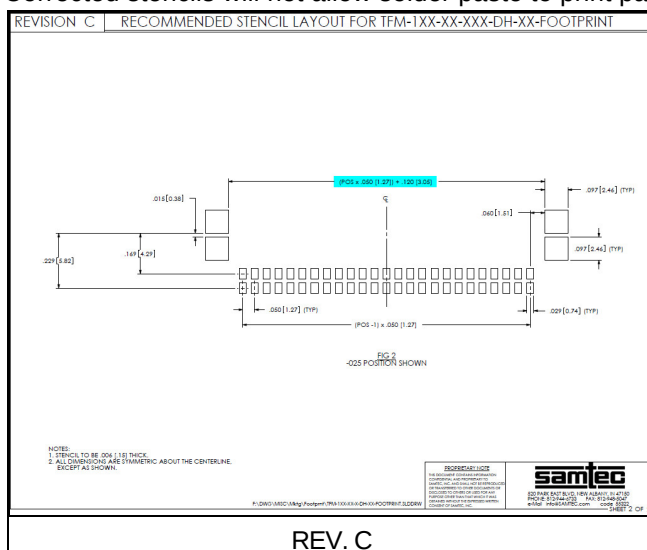
- TFM-1XX-XX-X-DH-XX

5. Description of Change:

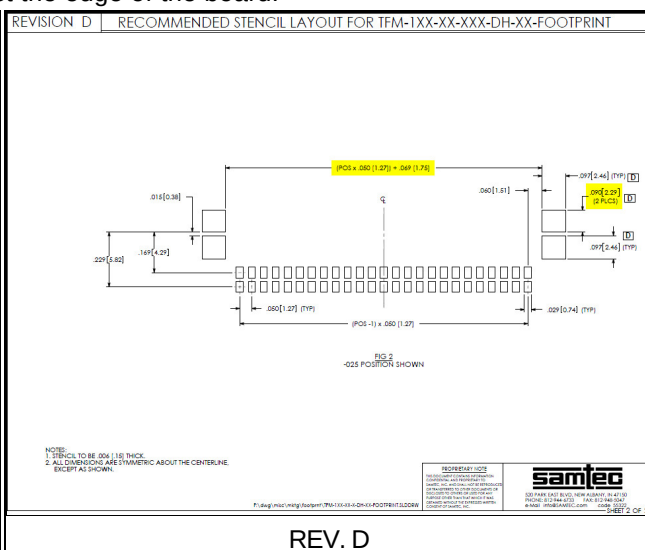
Weld tab aperture size and spacing is being changed to prevent solder paste from being printed off of the board.

6. Method of Identifying Change

Corrected stencils will not allow solder paste to print past the edge of the board.



REV. C



REV. D

7. Reason for Change:

This is a change to the stencil design only. The PCB footprint will remain as is.

8. Impact of Change on Form, Fit, or Function:

- Fit - The spacing and size of the weld tab apertures are being changed.

9. Projected Implementation Date: October 09, 2014